

Title (en)

USE OF A THERMALLY CURABLE AQUEOUS COMPOSITION AS A BINDER FOR SUBSTRATES

Title (de)

VERWENDUNG EINER THERMISCH HÄRTBAREN WÄSSRIGEN ZUSAMMENSETZUNG ALS BINDEMittel FÜR SUBSTRATE

Title (fr)

UTILISATION D'UNE COMPOSITION THERMODURCISSABLE EN TANT QUE LIANT POUR DES SUBSTRATS

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2007014906A1] The present invention relates to the use of a thermally curable aqueous composition comprising dispersed polymer particles of at least a) one polymer A1 containing 98-100% by weight of ethylenically unsaturated monomers A, where up to 20% by weight of the monomers A may contain glycidyl and/or hydroxyl groups and/or amine/amide groups and the polymer contains = 5% by weight of an α,β -ethylenically unsaturated mono- or dicarboxylic acid and at least 1% by weight of acrylonitrile in copolymerized form, and 0-5% by weight of a bi- or multifunctional monomer, and b) one polymer A2 which is soluble in serum and contains, in copolymerized form, 60-100% by weight of at least one α,β -ethylenically unsaturated mono- or dicarboxylic acid whose carboxylic acid groups may form an anhydride group, salts or mixtures thereof, c) and a polyfunctional crosslinker or mixtures thereof, d) and optionally di- or trivalent metal ions which are added in the form of hydroxides, oxides, carbonates or hydrogencarbonates, as binders for substrates.

IPC 8 full level

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